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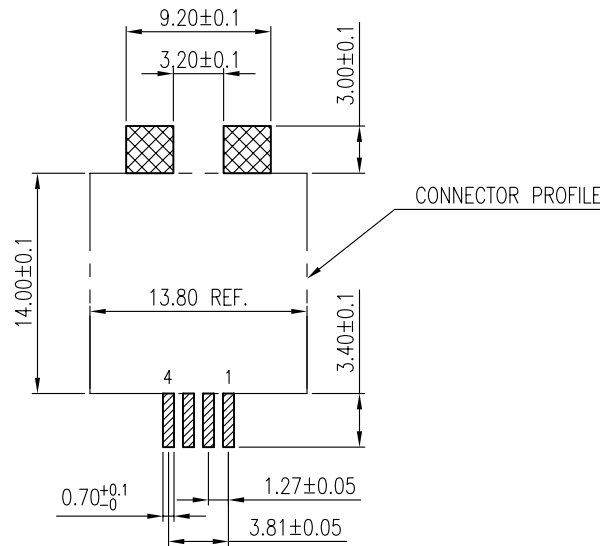
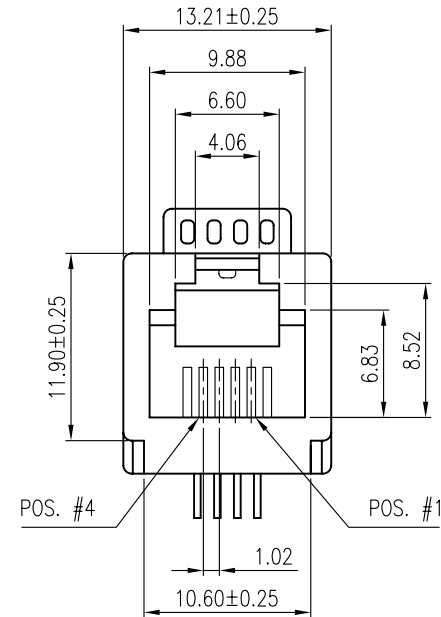
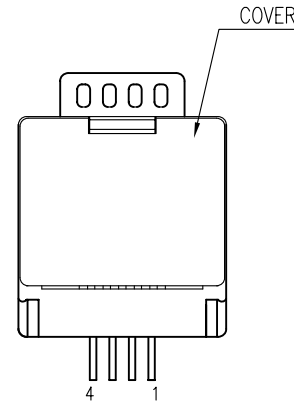
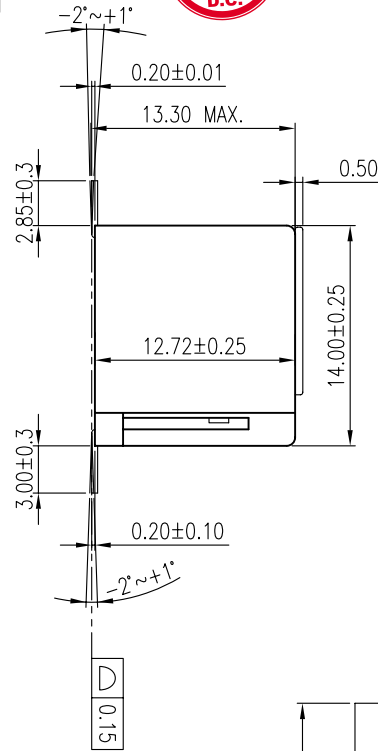
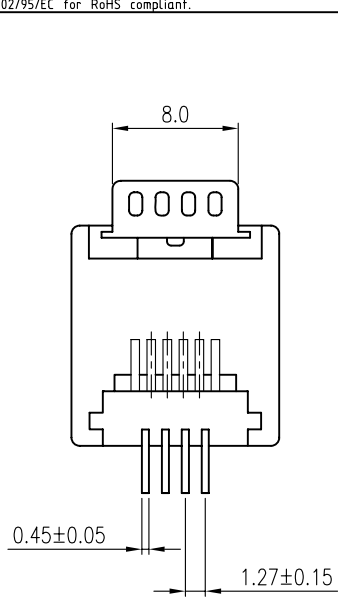
The marking on this product doesn't contain environmental hazardous materials per Material Specification SS-00259 for Sony GP compliant or per directive 2002/95/EC for RoHS compliant.



ORIGINAL



REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A		RELEASE TO PRODUCTION	10/30/2008	Hank Hsu



NON-COVER

NOTES:

- INSULATOR: NYLON 9T, UL 94V-0, COLOR- BLACK
- CONTACT: PHOSPHOR BRONZE, 0.35 MM THICKNESS, SELECTIVE GOLD PLATED ON CONTACT AREA, GOLD FLASH PLATED ON SOLDERING AREA, 50μ" MIN. NICKEL UNDER-PLATING OVERALL
- HOLD DOWN: COPPER ALLOY, 0.35MM THICKNESS, 100μ" MIN. TIN OVER 50μ" MIN. NICKEL UNDER-PLATING OVERALL
- COVER: NYLON-46, UL 94V-0, COLOR- BLACK
- THIS PRODUCT DOESN'T CONTAIN ENVIRONMENTAL HAZARDOUS MATERIAL PER DIRECTIVE 2002/95/EC FOR RoHS.
- THE PRODUCT MUST BE PER Amphenol PACKING SPECIFICATION PKS-0001

RECOMMENDED PCB LAYOUT (TOP VIEW)

G71C 0325 4 00 EU	50μ"
G71C 0325 3 00 EU	30μ"
G71C 0325 2 00 EU	15μ"
G71C 0325 1 00 EU	6μ"
PART NUMBER	FINISH

TOLERANCE	APPROVALS	DATE	TITLE	UNIT	SIZE	PART No.
X. X.X ±0.30 X.XX ±0.20 X.XXX ±0.10	DRAWN Sondra Sang	10/30/08	MODULAR JACK, 6P4C TOP ENTRY, SMT W/ HOLD DOWN & COVER	mm	A3	G71C 0325X 00 EU
	CHECKED Chenny Yeh	10/30/08				
ANGULAR ±1°	APPROVED Hank Hsu	10/30/08		SCALE	SHEET	DWG No.
UNLESS OTHERWISE SPECIFIED	DWG TITLE CUST DWG	PROJECT CODE MJK		NA	1 OF 1	G71C0325X00EU